GRAND VENTURE TECHNOLOGY

Corporate Presentation 2025

DISCLAIMER

This presentation may contain forward-looking statements which are subject to risks and uncertainties that could cause actual results to differ materially from such statements. Such risks and uncertainties include those arising from industry and economic conditions, competition, and legal, governmental and regulatory changes. The forward-looking statements reflect the current views of Management on future trends and developments. The information and opinions contained in this presentation are subject to change without notice.

The Company wishes to emphasise that none of the forward-looking statements in this document is intended to be a profit forecast and should not be treated as such.

HIGH PRECISION COMPONENTS, COMPLEX MECTRONICS & ASSEMBLY

Our solutions are key to the overall functionality of mission critical end products within

Semiconductor

Analytical Life Sciences

Medical

Aerospace

High Precision Products & Modules*

Chamber lid
Hinge bracket

Gripper substrate handler

Quadrupole
Vacuum chamber
Body interface
Ion guide

Microscope carrier
Base assembly
Vertical, horizontal arms
Heating element

Locking spring unit
Lock stay & cuff

Capital Equipment


CVD


Die bonder


Metrology


Mass spectrometer


High Performance Liquid Chromatography


Surgical Microscope


Flow Cytometry


Landing Gear

Mission Critical End Products


Chip Manufacturing (wafer fab, packaging, testing)


Drug Testing

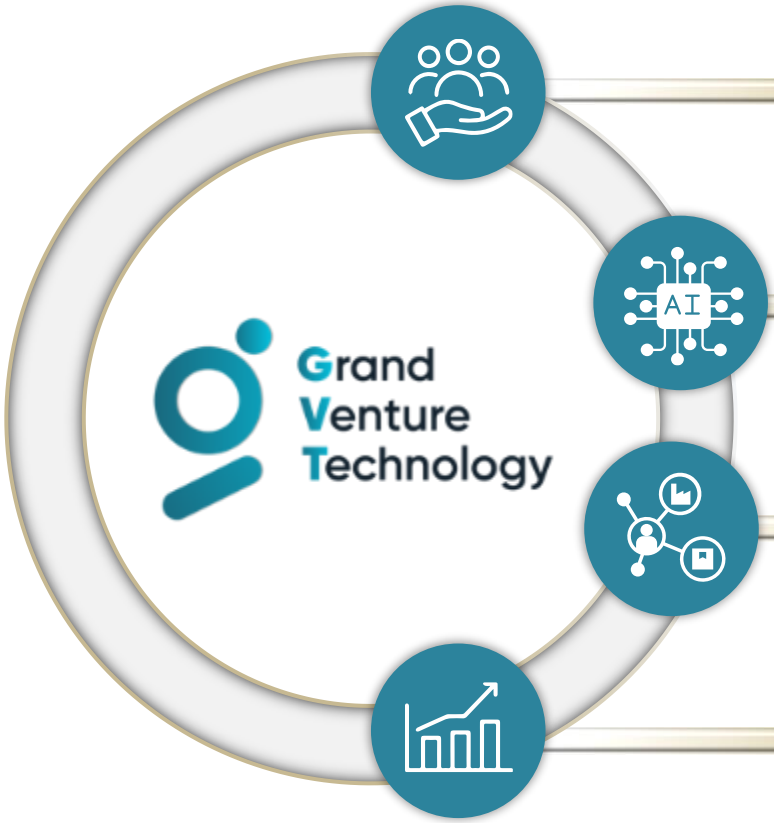

Medical Surgery


Commercial Airplanes

*List is non-exhaustive

PRECISION ENGINEERING SOLUTION PROVIDER FOR MISSON CRITICAL APPLICATIONS

Strategically positioned for multi-year growth



- Strategic partners to **blue-chip customers** across the semiconductor value chain from front-end to back-end
- Key beneficiary of AI and technological driven drivers in semiconductor - **Advanced Packaging and HBM**
- Semiconductor, aerospace, life sciences and medical segments benefitting from the **global supply chain reconfiguration**
- **Record revenue** of S$159.5 million (+43% YoY) in FY24; Strong 1HFY25 revenue guidance of S$90m – S$96m (+31.7% and +40.5% YoY increase)

COMPANY OVERVIEW

Powering the next generation technologies with our manufacturing solutions

Grand Venture Technology

Manufacturer of precision components and modules that power critical end segments, deeply entrenched **across the semiconductor value chain** as well as life sciences, aerospace, and others

KEY BLUE-CHIP CUSTOMERS(1)

Semiconductor (front & back-end)

Besi, Kulicke & Soffa, SAM, Reid Ashman

Leading Front-End Semi Equipment Maker

TERADYNE

Leading Front-End Semi Metrology Player

Life Sciences

SCIEX, ThermoFisher SCIENTIFIC

North American Life Science companies

EAMO(2)

BECKMAN COULTER, SAFRAN, Collins Aerospace

Global Producer of Surgical Microscopes

6 STRATEGIC MANUFACTURING SITES

S$159.5m
FY24 Revenue

S$30.6m
FY24 EBITDA(3)

c.1,800
Employees

c.818k sq.ft
Total size of facilities

Notes: (1) This list is non-exhaustive, (2) Electronics, Aerospace, Medical & Others (3) Adjusted EBITDA

KEY MILESTONES

2012 – 2016 "FOUNDATION"
S$0m - S$16m revenue

2012 **Established GVT SG**

2013 **Acquired GVT MY**

2014 **Approved supplier for Teradyne and Sciex** (Entry into Life Sciences)

2015 **Onboarded full sheet metal fabrication, painting & powder coating competencies**

2016 **Onboarded modular assembly competencies**

2017 – 2021 "DEVELOPMENT"
S$16m - S$116m revenue

2017 **Incorporated GVT Suzhou**

2018 **First article orders from ThermoFisher & Waters** (mass spectrometer components)

2019 **Listed on SGX Catalist**

2020 **Acquired additional Penang facility for front-end semi**

2021 **Raised S$52m via placements,** including S$24m from Novo Tellus – an Industrials Tech PE fund

Upgraded to SGX Mainboard

2022 – 2025 "ACCELERATION"
S$116m - ? revenue

2022 **Acquired J-Dragon:** entry into Aerospace

Acquired Formach: Sheet metal competency for front-end semi

2023 **Onboarded multiple new marquee front-end customers** across etch, deposition and metrology

2024 **Acquisition of ACP:** surface treatment specialist for front-end semi and Aerospace

2025 **Advanced ceramics development:** Partnered research institute A*Star

Awarded critical advanced front and back-end semi projects (TSV and TCB)

KEY MANAGEMENT TEAM

Led by seasoned entrepreneurs that came together, backed by a track record of building companies

Lee Tiam Nam, Ricky

Executive Deputy Chairman & Co-Founder

- **Industry veteran with 40+ years of experience**
- Founded and held leadership positions across multiple firms while playing pivotal roles in their IPO and sale:
  - Co-founded Norelco Centreline that was listed on SGX Catalist and merged with UMS Holdings
  - Executive director at ETLA that was listed on SGX before being acquired by Frencken Group

Ng Wai Yuen, Julian

Chief Executive Officer, Executive Director & Co-Founder

- **20+ years of industry experience**
- Worked with Ricky for 20+ years in leadership positions across different firms such as ETLA and Norelco Centreline
- Previously founded Achieve Manufacturing Solutions that was acquired by ETLA

Tan Chun Siong

Chief Operating Officer & Co-Founder

- **20+ years of industry experience**
- Worked with Ricky for 15+ years across different firms such as ETLA and Norelco Centreline
- Previously served at Apple SA, ETLA and Norelco Centreline

Robby Sucipto

Chief Financial Officer

- **17+ years of financial audit and M&A experience**
- Previously served at Ernst & Young, KPMG, a group company of Hitachi and Pacific Star Development Limited

Leong Kwok Choon

Chief Technology Officer

- **30+ years of industry experience**
- Worked with Ricky for across different firms such as ETLA and Norelco Centreline
- Previously served at Frencken, UMS, Flex and Philips

Saw Yip Hooi

Managing Director (Malaysia) & Co-Founder

- **30+ years of industry experience**
- Worked with Ricky for 15+ years across different firms (Norelco Centreline and GVT MY)
- Previously served at Norelco Centreline, Ultimate Manufacturing Solutions and GVT MY

Lu Jin Feng, Alan

General Manager (GVT Suzhou)

- **20+ years of industry experience**
- Previously served at Hongguan Technologies Machinery (Suzhou), VDL Enabling Technologies Group (Suzhou)
- Previously founded SIP Innovation and Excellence that was acquired by GVT

Lee Boon Kwong Wilson

Managing Director (GVT Suzhou Limited)

- **30+ years of industry experience**
- Previously served at Norelco Engineering Services, Super Union Precision Engineering
- Co-founded Certact Engineering and J-Dragon, with the latter acquired by GVT in Mar-22

SELECTED CORE COMPETENCY ILLUSTRATION

Sub-micron machining

What is Sub-Micron Machining & Importance

- A high-precision manufacturing process: materials are processed at an atomic scale, in the vicinity of one micron (for scale, a human hair is 20 – 70 microns)
- Requires the use of single crystal diamond tools for ultrafine cutting or very fine abrasives for lapping or polishing
- Critical for high-value processes such as chip making and drug discovery
- **Few microns difference might result in substantial dollar loss**
  (i.e., micron gaps within gas delivery chambers in mass spectrometers might result in leakage or cross contamination that will yield inaccurate results).

End Application: Mass Spectrometer

Selected Components that GVT Manufactures

Quadrupole Mass Filter
Ion Source
Q2 & Entrance Lens

GVT Value Proposition

Provides one stop solution from ultra-precision mechanical component fabrication and sub-micron measurement, design and fabrication of assembly jigs for laser welding and precision assembly alignment

Requirements down to **tenths of a micron in a clean room environment**.

Sources: IPO prospectus, annual reports, company info

OUR KEY PROCESSSES

Grand Venture Technology

Design for Manufacturability/ Assembly

Manufacturing

Surface Treatment

Assembly & Testing

MACHINING

Precision **cutting, machining, and finishing** of materials such as metals, engineering plastics, ceramic, and quartz

SHEET METAL

Cutting, shearing, rolling, bending, punching, welding, and painting of sheet metal

At sub-micron level, including vacuum parts

Key components for mission critical end products

Plating

Sandblasting

Anodising

Self-manufactured Components + 3rd Party Components

Advanced mechatronics and high value assembly

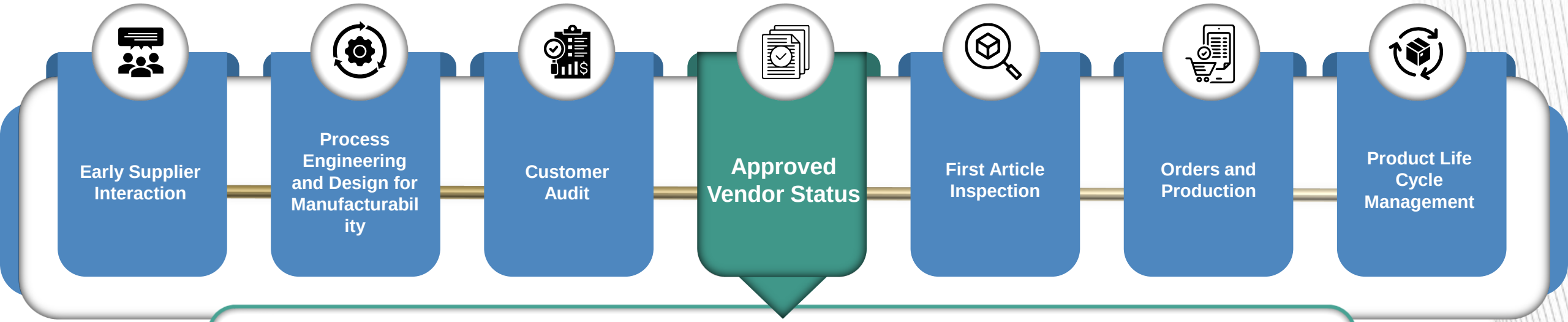
Key modules for mission critical end products

THE VENDOR OF CHOICE FOR BLUE-CHIP CUSTOMERS

Well-positioned to capitalize on the next semiconductor upcycle

Long gestation period and stringent process to win customers give incumbents like GVT a strong moat

Trusted with product roadmaps, strong ties with customer local and global R&D, engineering and procurement teams



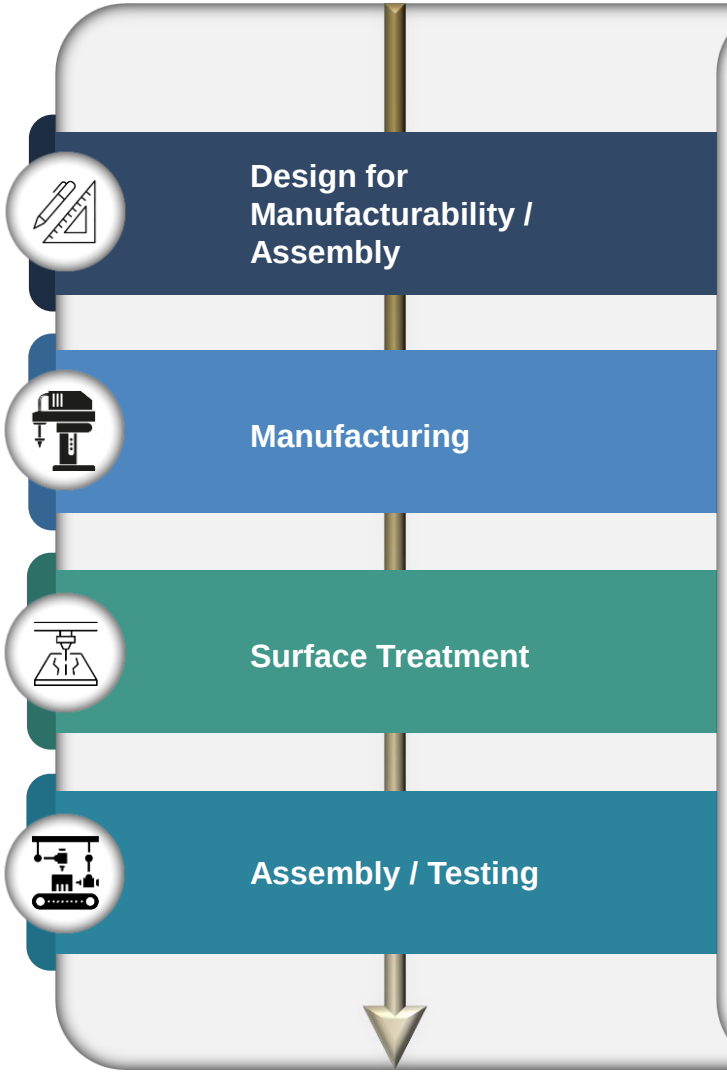
GVT's typical customer product life is >10 years, where it is involved in:

New products: improve technical performance, functionality and durability

Existing products: improve efficiency, margins and extend product life cycle

OUR CORE CAPABILITIES

Comprehensive end-to-end capabilities enabled us to wallet share across new and existing customers



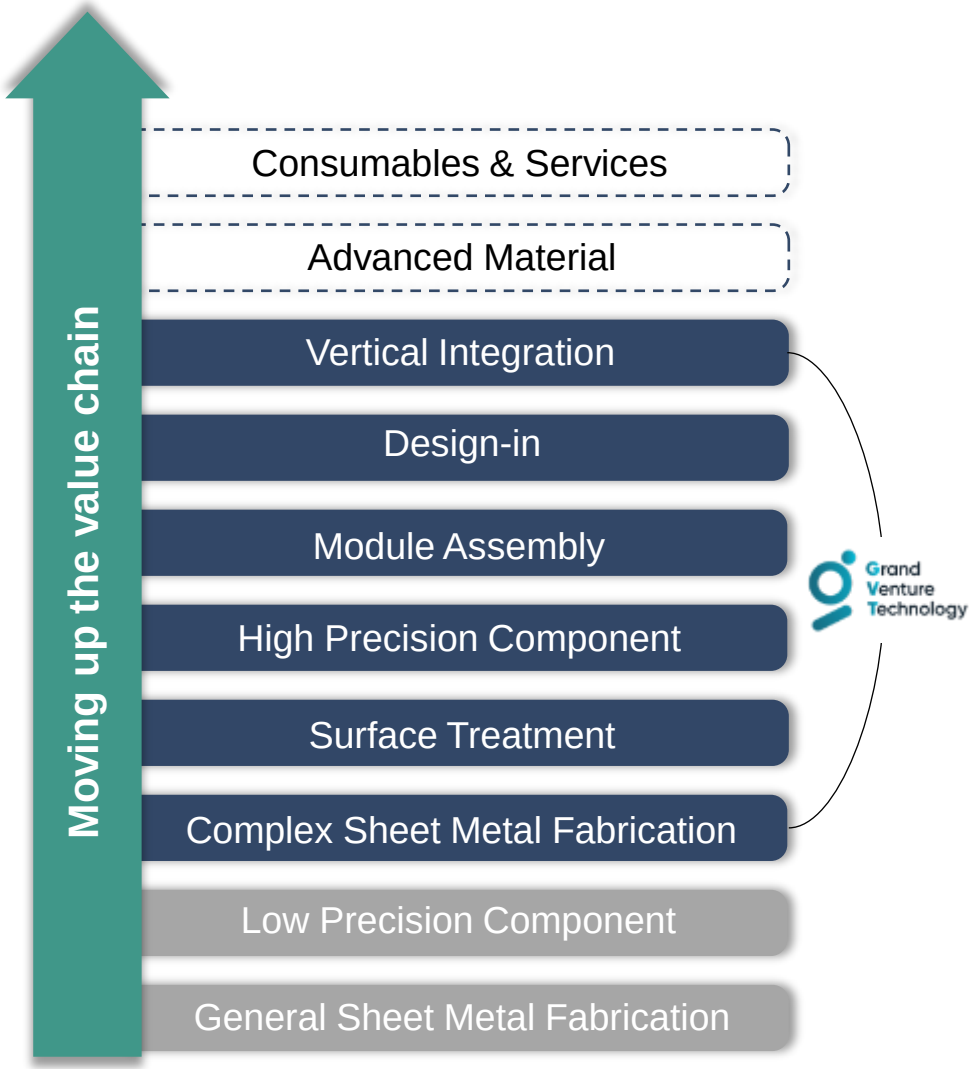
Capabilities	Semiconductor	Life Sciences	Aerospace	Electronics, Medical and Others
Design for Manufacturability / Assembly	✓	✓	✓	✓
Ultra Precision Machining (Sub-micron)	✓	✓		O
High Precision Machining	✓	✓	✓	✓
Vacuum Parts Manufacturing	✓	✓		
Ultra-high Vacuum Production Processing	✓	✓		
Engineering Plastic, Ceramics, and Quartz Machining	✓	✓	O	✓
Complex Sheet Metal Fabrication	✓	✓	O	✓
Surface Treatment	✓	O	✓	
Assembly (Medium - High Complexity)	✓	✓	O	✓
Assembly (High Complexity in Class 10K Cleanrooms)	O	✓		
Customized Engineering Solutions	✓	✓	✓	✓

✓ Existing services provided

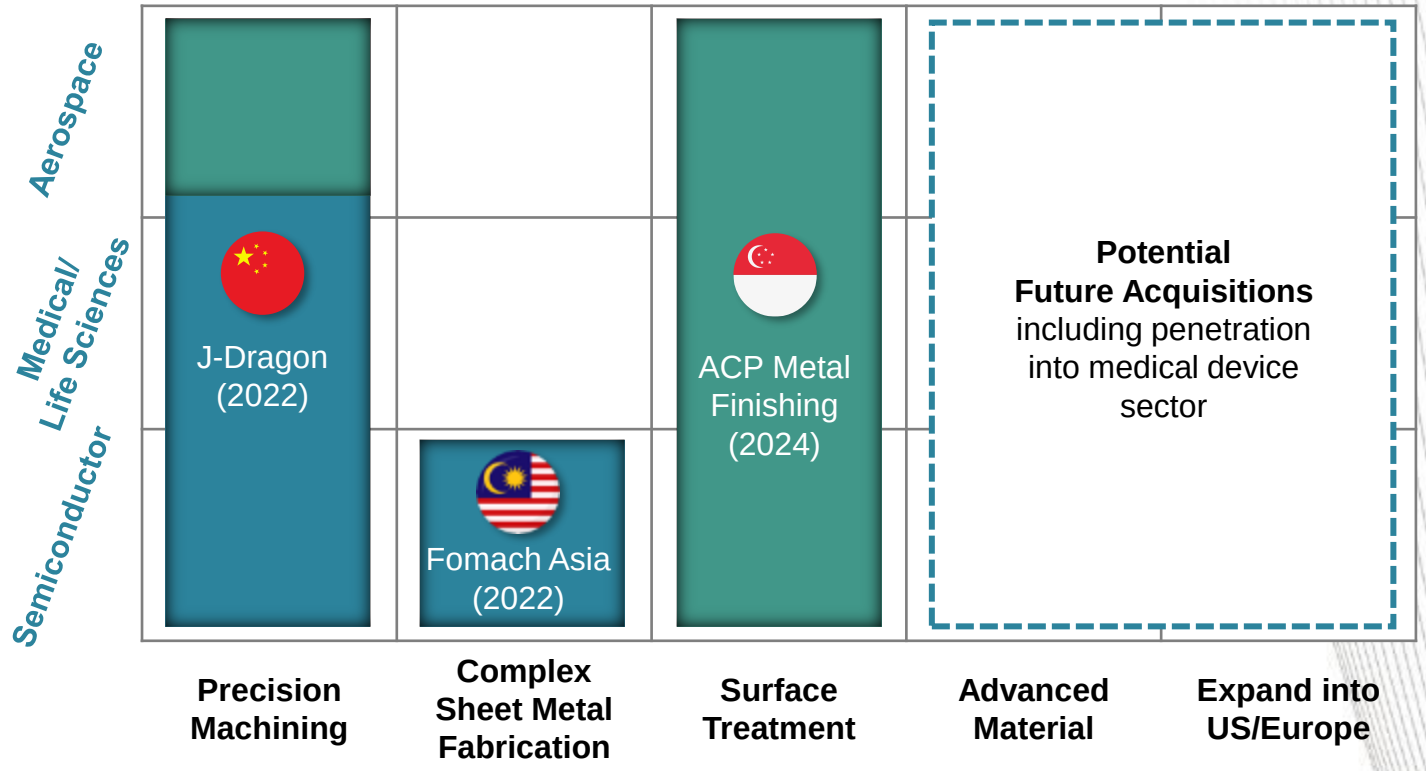
O Cross-selling opportunity from existing capabilities

ENHANCING CAPABILITIES AND EXPANDING OFFERINGS

Moving up the value chain through organic and inorganic growth



Transformative acquisitions since 2022



Expanding market and wallet share through capabilities extension

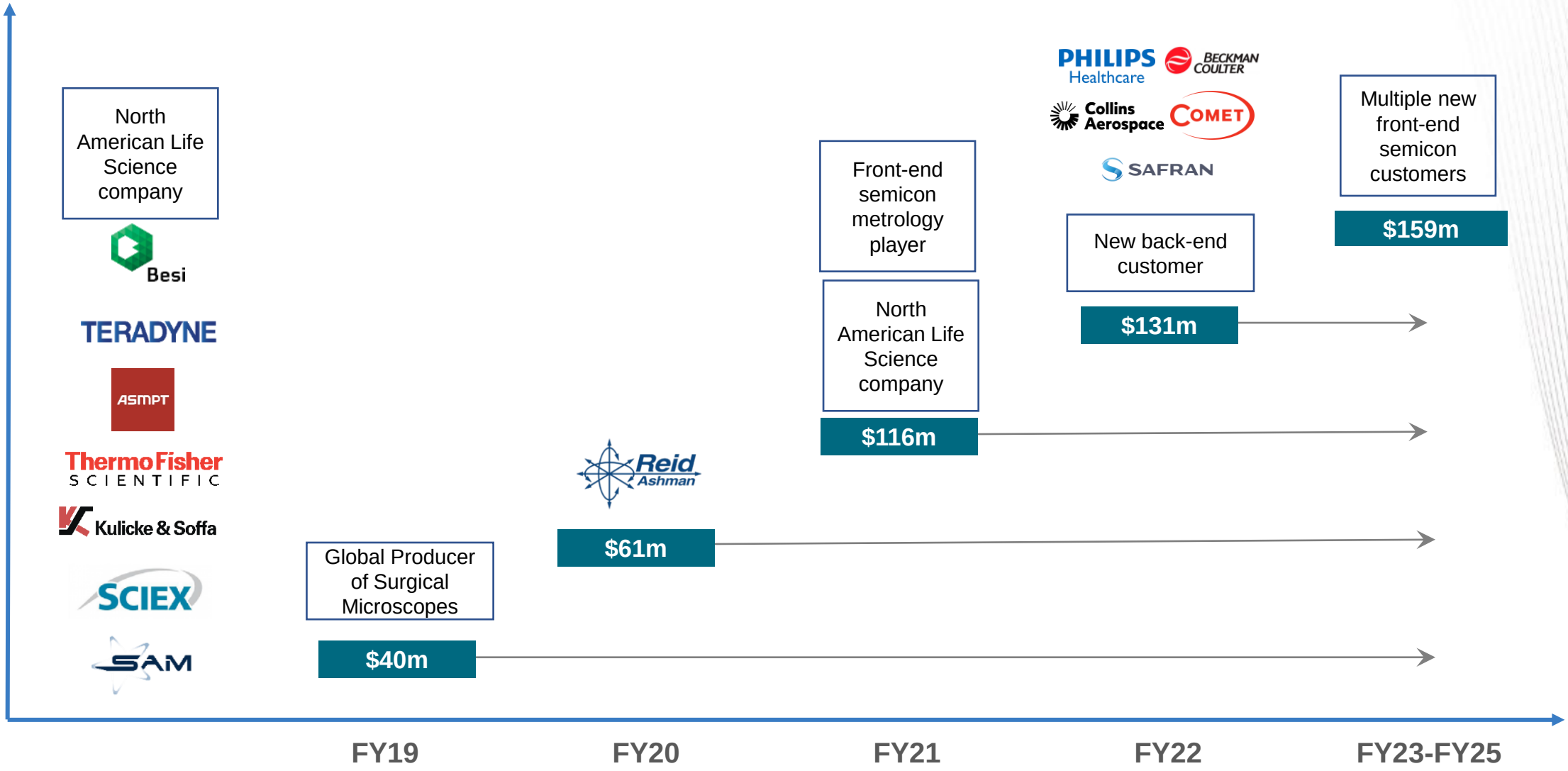
Non-focus competency | Current competency | Growing competency

Added capabilities since 2022 | Enhanced capabilities since 2022

TRACK RECORD OF CAPTURING NEW US & EU BLUE CHIP CUSTOMERS

Grand Venture Technology

Successfully grew wallet share with no churn



Sources: IPO prospectus, annual reports, company info

Grand Venture Technology

INDUSTRY OUTLOOK

OUR EXPOSURE TO THE SEMICONDUCTOR VALUE CHAIN

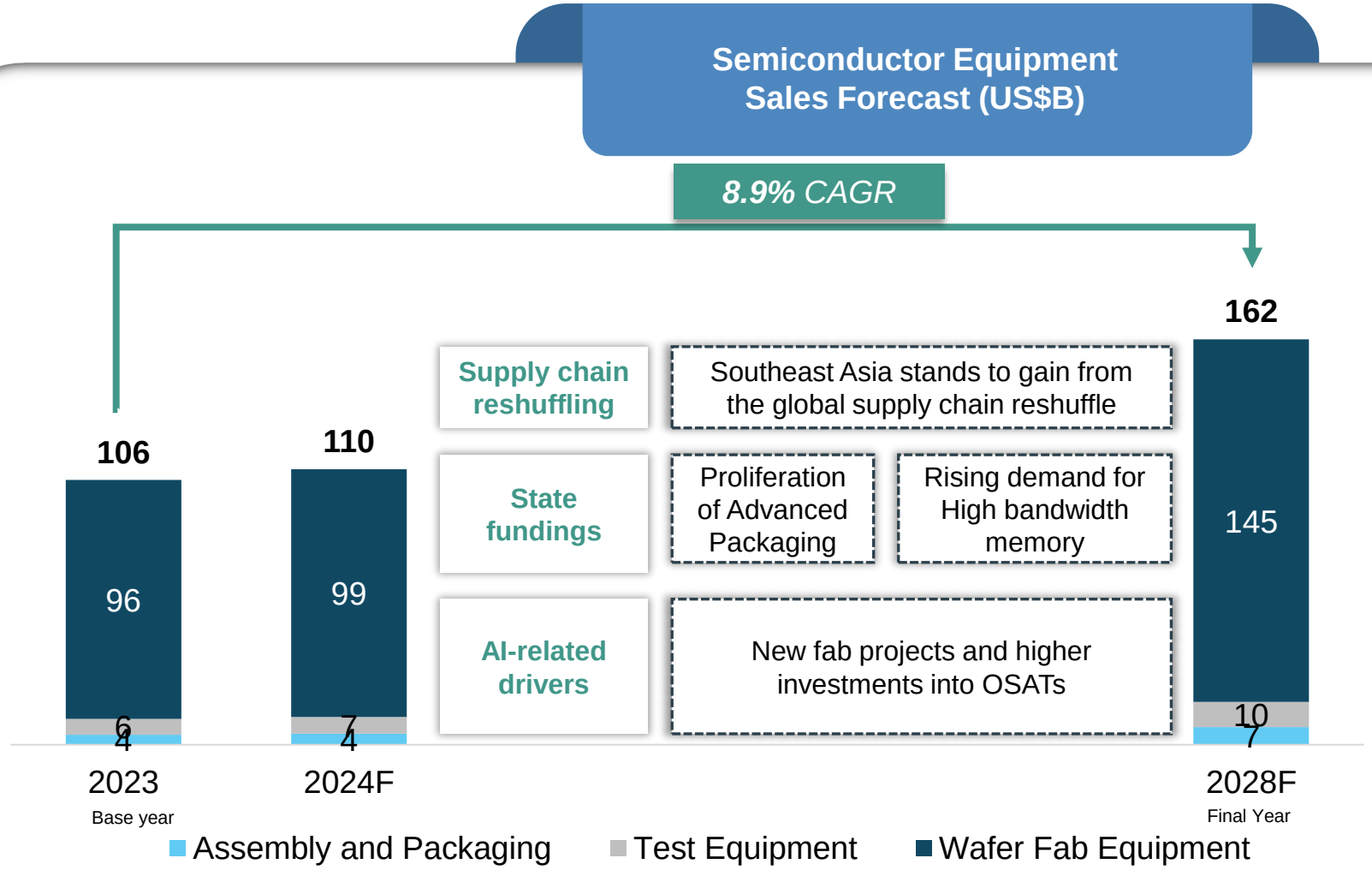
Deep engagements with blue-chip customers across the semiconductor equipment space

	FRONT-END (WAFER FAB)			BACK-END (ASSEMBLY & TEST)		
	US$98Bn[1] Front-end refers to the fabrication process of the main structures of the IC. Value of **front-end equipment is 10x vs back-end equipment**			**US$11Bn[1]** Back-end process involves the interconnection, packaging, and testing of the manufactured semiconductor chips.		
Process	**Lithography**	**Etching**	**Deposition**	**Inspection and metrology**	**Die Attach**	**Wire Bonding**	**Testing**
Customers		**Key Wafer Fab Equipment Provider**	**Key Wafer Fab Equipment Provider**	**Key Semi Metrology Equipment Provider**	Besi	Besi KK	TERADYNE
Customer's Market Share		**50%[2]** *in 3D HBM*	**50%[2]** *in 3D HBM*	**55%[3]** *in optical inspection*	**43%[2]**	**22%[2]** **60%[4]**	**Duopoly-like with Advantest[5]**
Example of GVT's leading edge projects	**Through Silicon-Via, Atomic Layer Disposition, High-Precision (2D & 3D) Surface Metrology**				**Thermal Compression Bonding, Hybrid Bonding, High Bandwidth Memory Testing**		

Sources: [1]SEMI (2024 Equipment Market Size), [2]Company presentations, [3]Gartner [4]Semiconductor Engineering, [5]Morningstar

SEMICONDUCTOR EQUIPMENT SPEND IS ACCELERATING

Multi-year growth expected on the back of strong secular growth drivers and exposure across the value chain



Supply chain reshuffling

Southeast Asia stands to gain from the global supply chain reshuffle

State fundings

Proliferation of Advanced Packaging

Rising demand for High bandwidth memory

AI-related drivers

New fab projects and higher investments into OSATs

GVT is well positioned as a **key beneficiary across the entire value chain** with:

1. Front-end entry;
2. Strategic MY and SG sites;
3. Established leadership in back-end that is amplified with increasing convergence between front and back-end.

Sources: Protégé, Semi

LIFE SCIENCES AND AEROSPACE SEGMENT RIPE FOR GROWTH

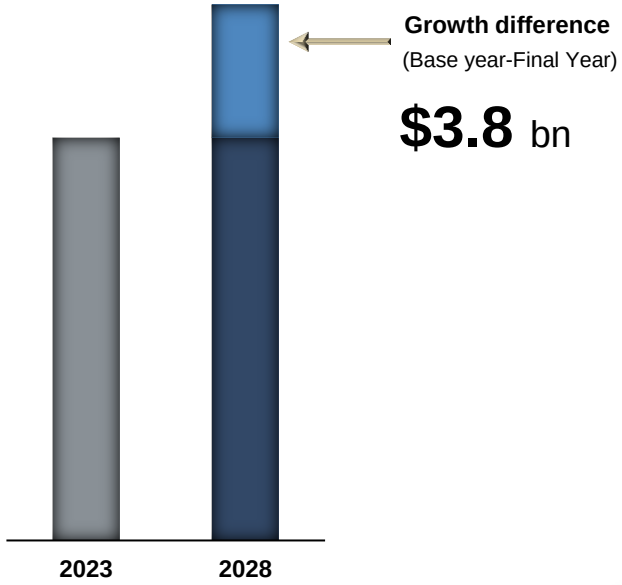
Diversified customer base in high growth areas will drive long-term growth for GVT

Life Sciences

Incremental market growth expected for our key addressable tools

- Healthcare reforms with streamlined and faster regulatory approval processes
- Ageing population and prevalence of chronic illnesses

Global Mass Spectrometry Market

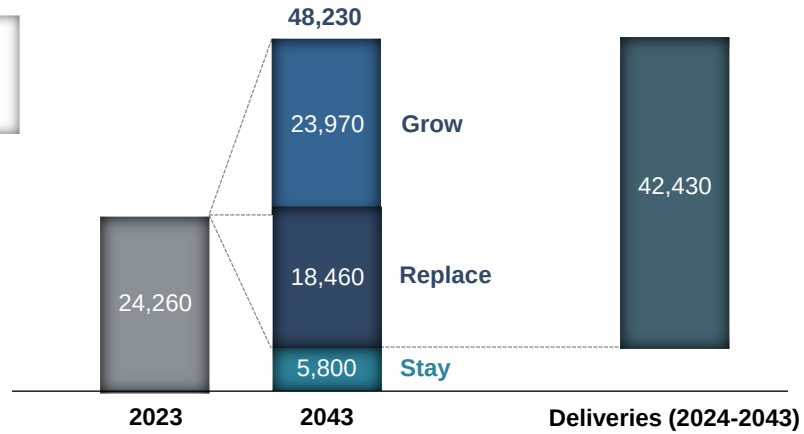


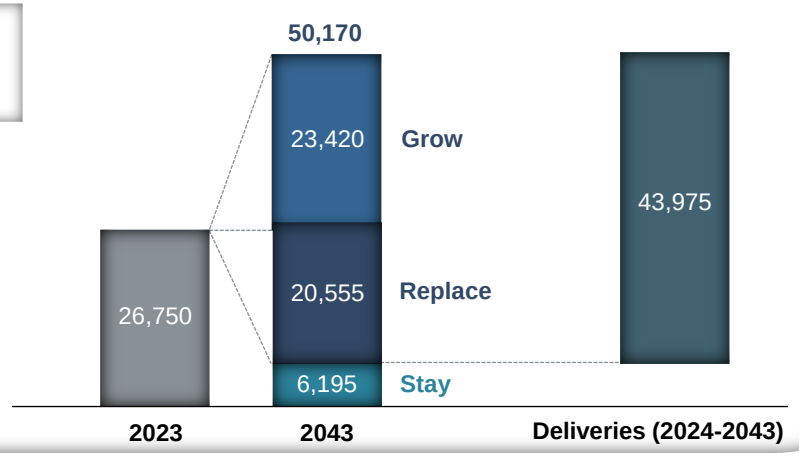
CAGR of (2023-2028)

10.0%

Aerospace

Global aircraft fleet to double over the next 20 years





Sources: BioSpace, Technavio, Airbus, Boeing

SECULAR GROWTH DRIVER – AI DEVICES

Rising importance of AP and HBM will drive packaging and testing equipment demand

Artificial Intelligence is creating technological challenges which are enabled by AP and HBM

Rising Complexity

Chips are becoming more complex to enable next generation technologies

Miniaturization of Semiconductor Devices

Stacking of chips is reducing the size of semiconductor devices

Thermal Management

Smaller form factor generates more heat creating a need for thermal management

Rising Customization Demand

Higher demand for customizable solutions to support application specific configurations

Higher demand for 2.5D/3D packaging equipment

Besi

Key Wafer Fab Equipment Provider

Higher demand for new generation testing equipment

TERADYNE

Higher demand for complex, high-precision components

Grand Venture Technology

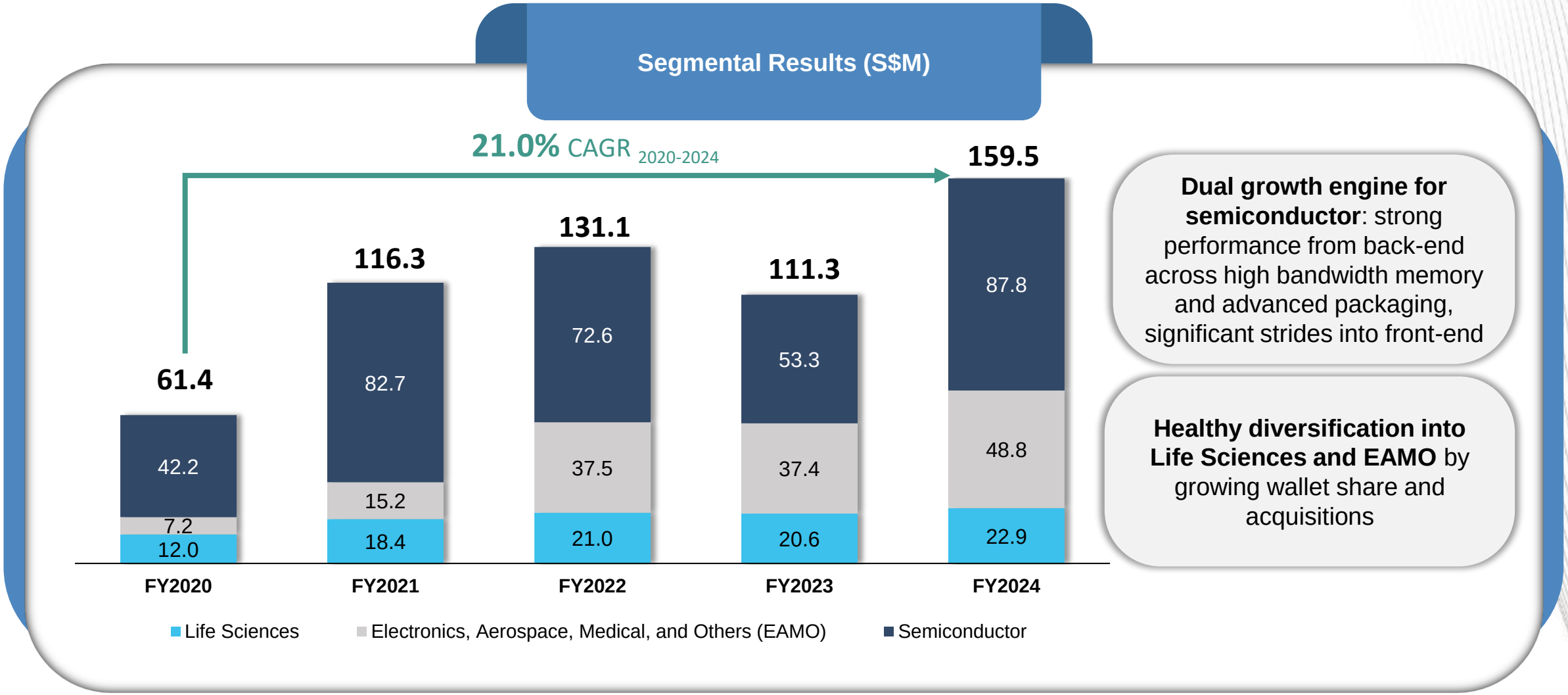
AP: Advanced Packaging; HBM: High Bandwidth Memory

Grand Venture Technology

FINANCIAL RESULTS & COMPANY HIGHLIGHTS

POISED TO CAPITALIZE ON SEMI UPCYCLE

Poised to continue winning new programs and wallet share across its core segments, especially semiconductor



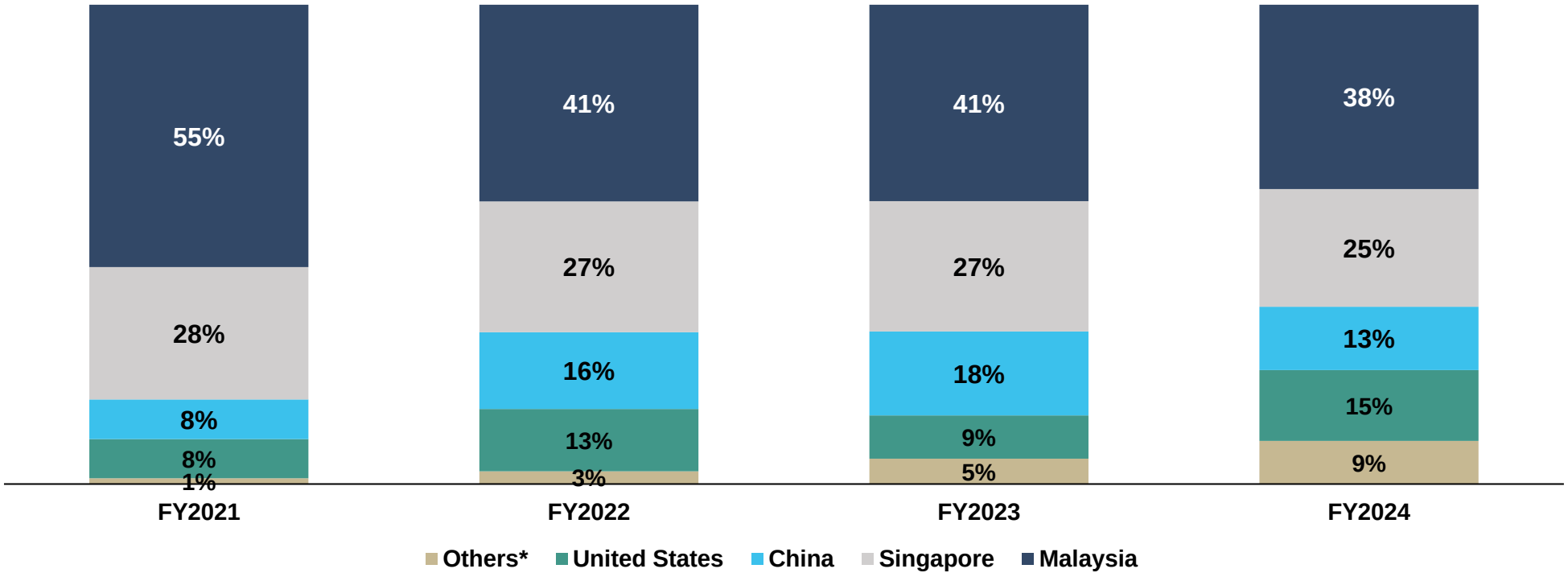
Dual growth engine for semiconductor: strong performance from back-end across high bandwidth memory and advanced packaging, significant strides into front-end

Healthy diversification into Life Sciences and EAMO by growing wallet share and acquisitions

MALAYSIA IS OUR CORE MARKET CATERED FOR SEMICONDUCTOR

GVT mainly serves the global MNCS who have a production base in SE Asia

Revenue by geographical markets (% of total)

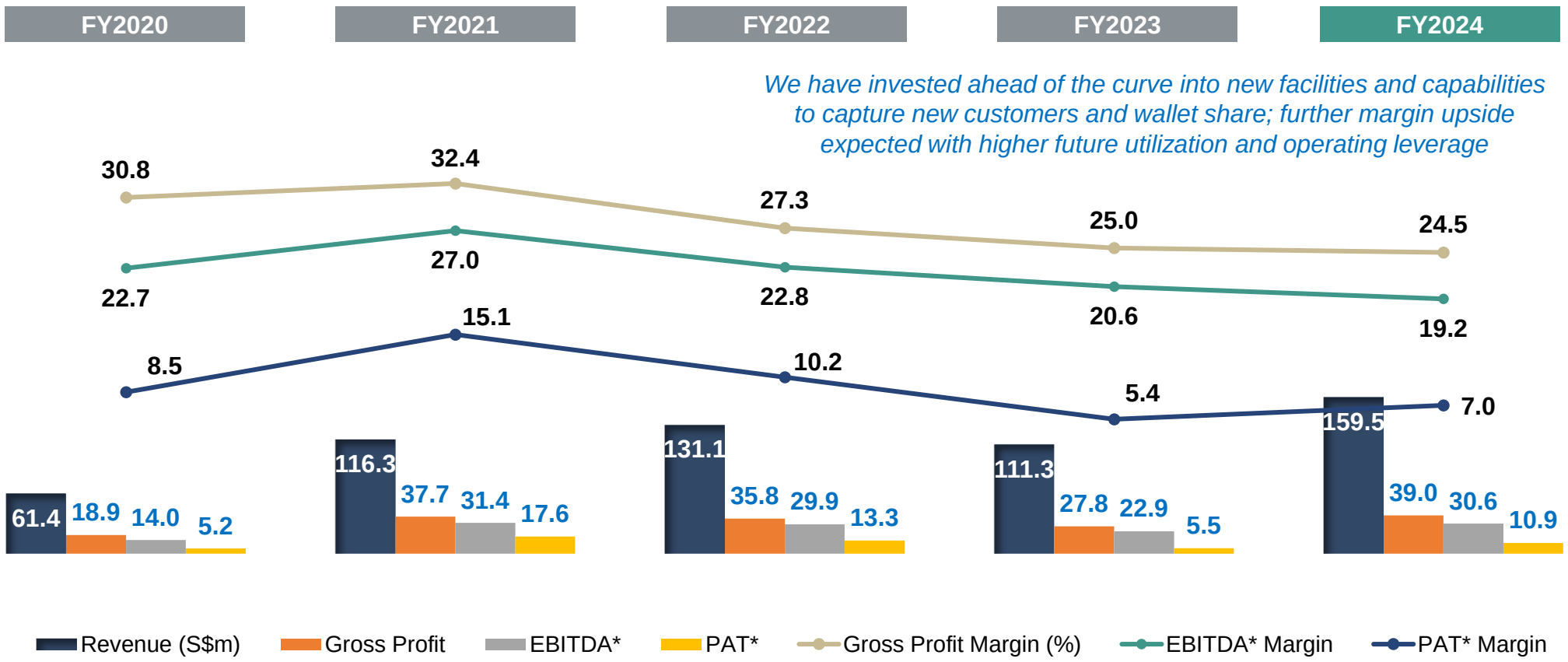


Note: *Canada and Netherlands

OPERATING LEVERAGE TO PAVE WAY FOR PROFITABILITY

Margins set to return to the higher-end, with improved utilization from cyclical recovery and new programs

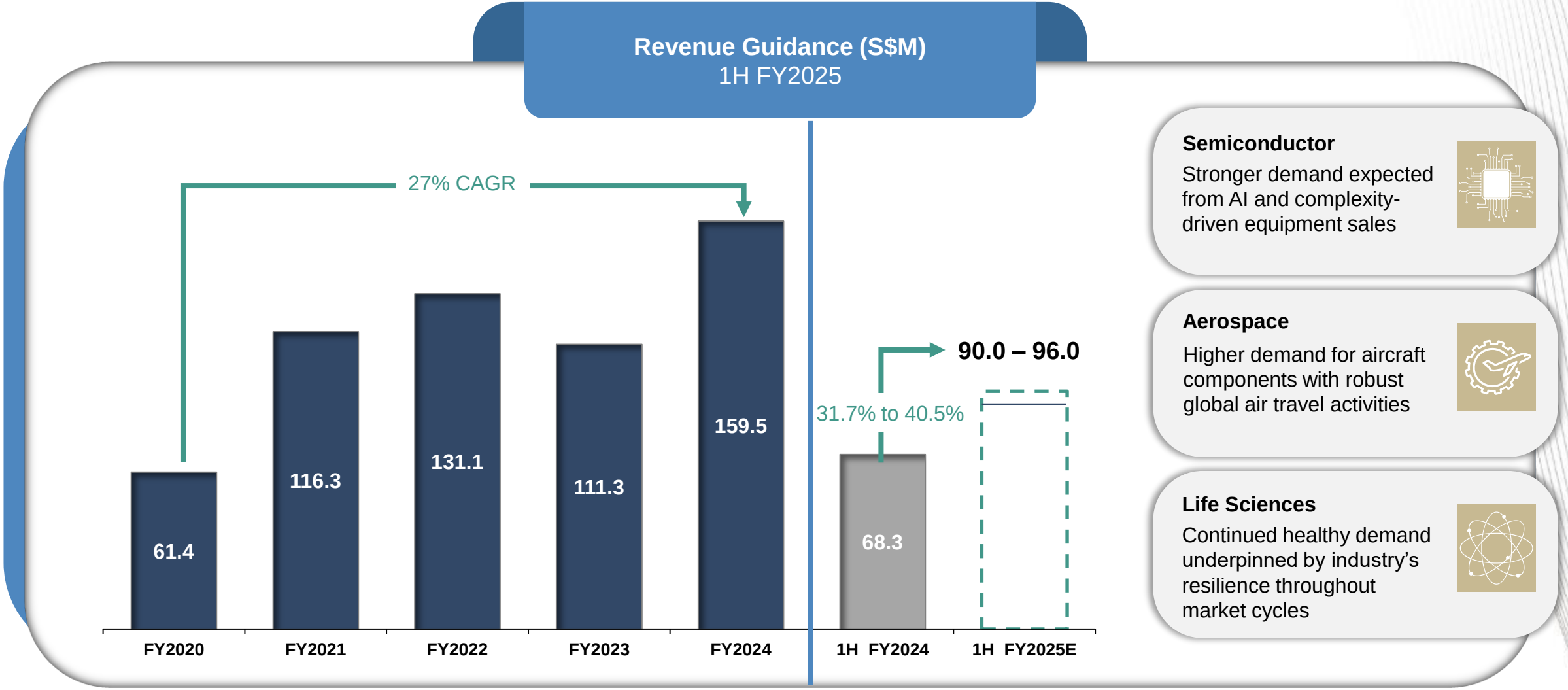
Revenue & Profit Margins (1)



Notes:
* EBITDA, EBITDA margin, PAT and PAT margin for FY2023 and FY2024 refers to the adjusted levels to better reflect the Group's underlying earnings
(1) Gross profit margin (GPM) includes labour (variable), material (variable), and factory overheads (fixed)

REVENUE PERFORMANCE AND GUIDANCE

4Y CAGR of 27%, with the strong momentum expected to continue into FY2025



Semiconductor

Stronger demand expected from AI and complexity-driven equipment sales

Aerospace

Higher demand for aircraft components with robust global air travel activities

Life Sciences

Continued healthy demand underpinned by industry's resilience throughout market cycles

INVESTMENT HIGHLIGHTS

Veteran management team
Experienced team who has experience in delivering strong design engineering proposition with progressive mindset to innovate

Large addressable market driven by tailwinds
Led by blue chip customer's end market growth and technology supply chain shifts to SEA

Blue chip customer base
Sticky customer relationship with top global equipment makers across semiconductor, life sciences, medical and electronics

Robust financial profile and growth record
Has grown revenue and net profit by more than 3x since 2019

Strong acquisition track record
Acquired 5 companies across 3 geographies since founding in 2012 with all previous founders staying with the business.

Future growth from nascent segments
Early multi-year investments in front-end semiconductor and life science capabilities are starting to pay off with expected near-term ramp

A compelling investment opportunity well positioned for future growth

Grand Venture Technology

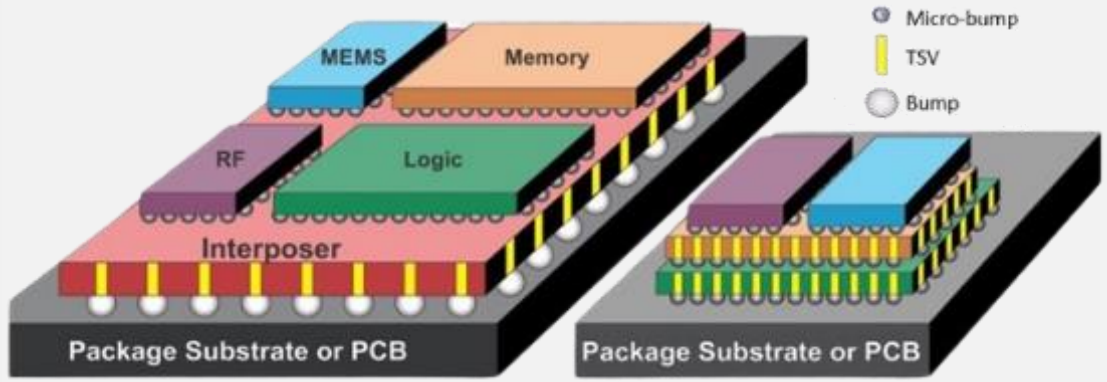
THANK YOU!

Grand Venture Technology

APPENDIX: INDUSTRY

GROWTH ENABLER – ADVANCED PACKAGING

Advanced Packaging is becoming increasing important to address complexity challenges in AI devices



2.5D Packaging

Chips are **placed side by side** on a common **interposer**, which connects them electrically.

3D Packaging

Chips are **stacked vertically** on top of each other, connected using **TSVs** .

AP and its advantages

AP focuses on integrating multiple chips or components in a single package to improve chip performance and power efficiency

- **Better Performance**
- **Higher Cost Savings**
- **Miniaturization**
- **Better Heat Dissipation**

Higher demand for metrology and TSV

Ensuring precise alignment, layer thickness and bonding

Need for new tools optimized for 2.5D/3D packaging

Drive replacements across existing and new fabs

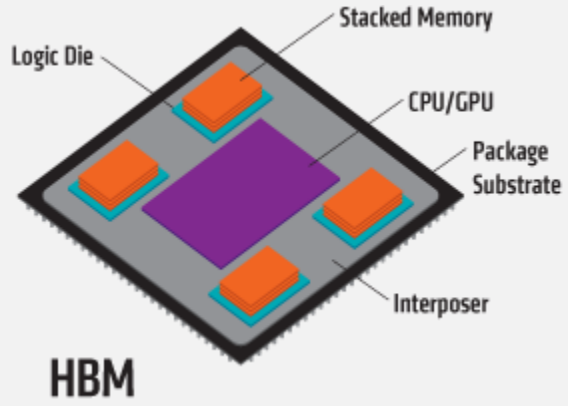
Higher demand for hybrid bonders, TCB, metrology tools → Grand Venture Technology

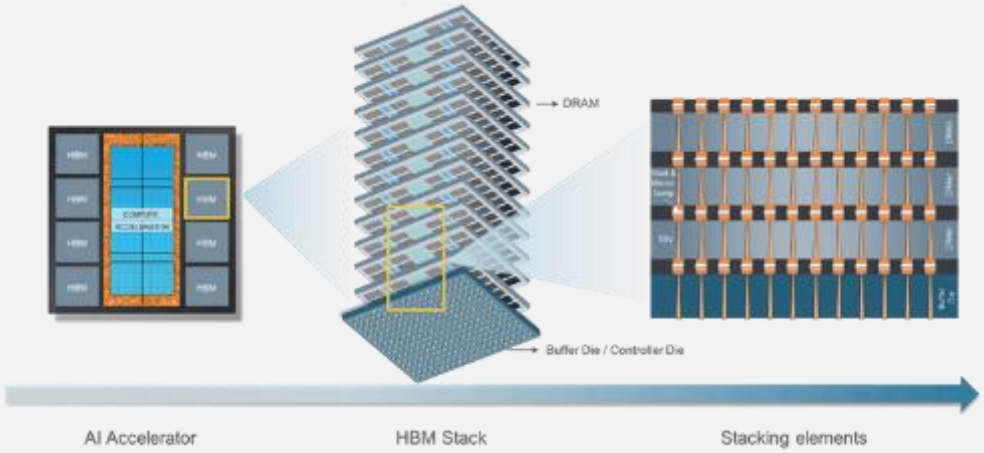
Picture Source: Siemens Technical Paper (Automated ESD protection verification for 2.5D and 3D ICs)

TSV: Through-Silicon Via; TCB: Thermal Compression Bonding

GROWTH ENABLER – HIGH BANDWIDTH MEMORY

HBM will create incremental demand for 2.5D/3D packaging and TSVs due to increasing miniaturization





HBM and its advantages

High Bandwidth Memory (HBM) is a dense, stacked version of memory with high-speed interface and lower power consumption

- **Higher Bandwidth**
- **More Power**
- **Smaller Form Factor**
- **Reduced Latency**

Higher demand for metrology tools

Slow throughput and lower yield

Greater testing requirement

Individual chip testing + testing once chips are stacked

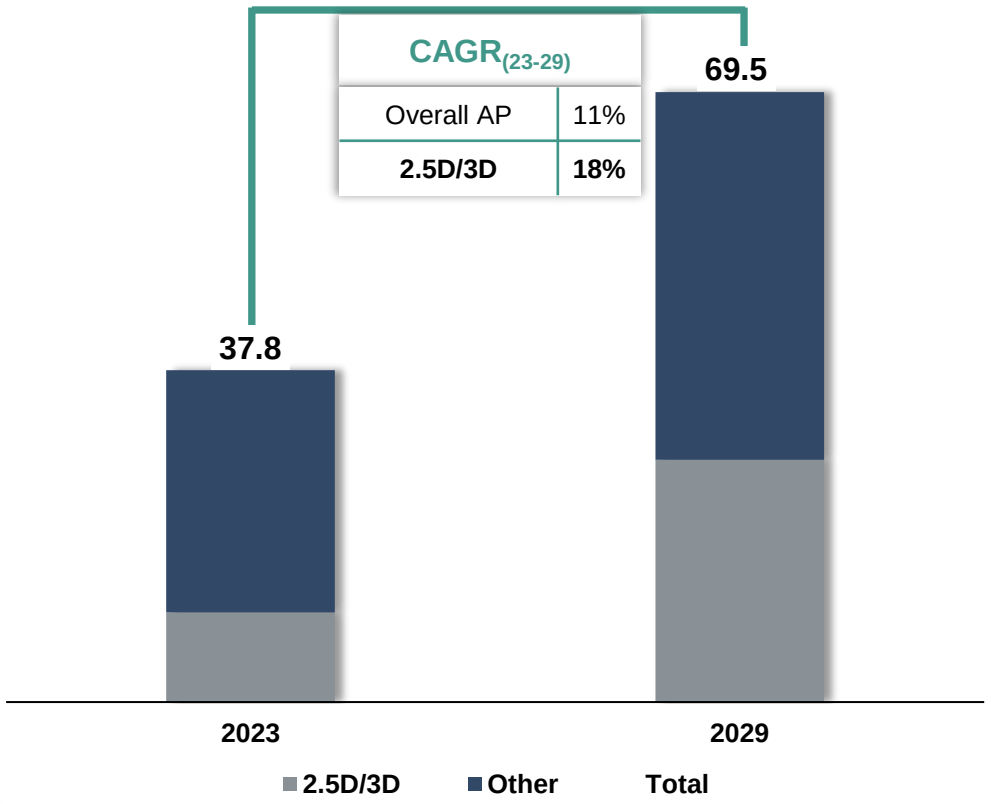
Higher demand for metrology tools and testing equipment

Picture Source: Applied Materials

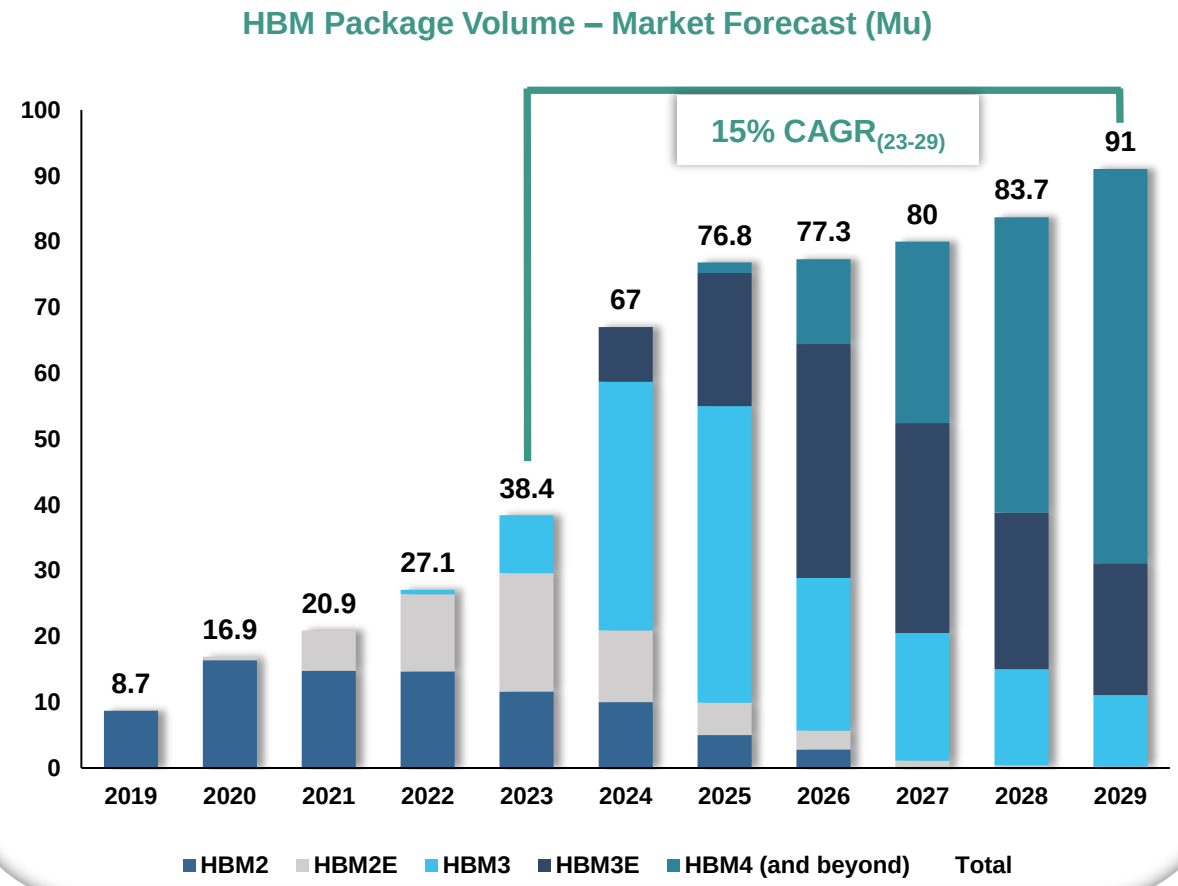
PROMISING MARKET FUNDAMENTALS

Multi-year growth expected for both Advanced Packaging and High Bandwidth Memory

2.5D/3D to drive overall AP market growth (US$B)



HBM3E/4 and beyond expected to drive volume growth



Sources: Yole November 2023 and July 2024